

# RL78 Software Migration Guide

R01AN3954EJ0101

Rev. 1.01

Source Code Migration from Assembly Language to C Language CC-RL

Jan. 23, 2018

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## Introduction

This application note describes how to migrate the program in the assembly language for the CS+, which is the integrated development environment (IDE), to the inline assembler functions in the C language.

As a migration example, the sample program covered in the application note RL78/G10 Timer Array Unit (Interval Timer) CC-RL (R01AN3074E) is used.

## Target Device

RL78 Family

When using this application note with other Renesas MCUs, careful evaluation is recommended after making modifications to comply with the alternate MCU.

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## 1. Procedure for Migrating Source Code from Assembly Language to C Language

The following describes the procedure for migrating the program in the assembly language for the IDE CS+ to the inline assembler functions in the C language. First of all, create a new project by using a code generation tool of the IDE CS+ C compiler CC-RL. Replace the constants, variables, and functions of the assembly source code with the constants, variables, and inline functions of the C language code, respectively.

### 1.1 Automatic Source Code Generation

Source code can be automatically generated by using the code generation tool of the IDE CS+ C compiler CC-RL. Refer to the assembly source code to be replaced and set the code generation tool.

- (1) Click "Clock Generator" under Code Generator (Design Tool) on the Project Tree pane (A in Figure 1.1).
- (2) Perform "Pin assignment" and click the [Fix settings] button (B in Figure 1.1).

Note: To set the other functions, Pin assignment needs to be performed. Once Pin assignment is decided, it cannot be changed later.

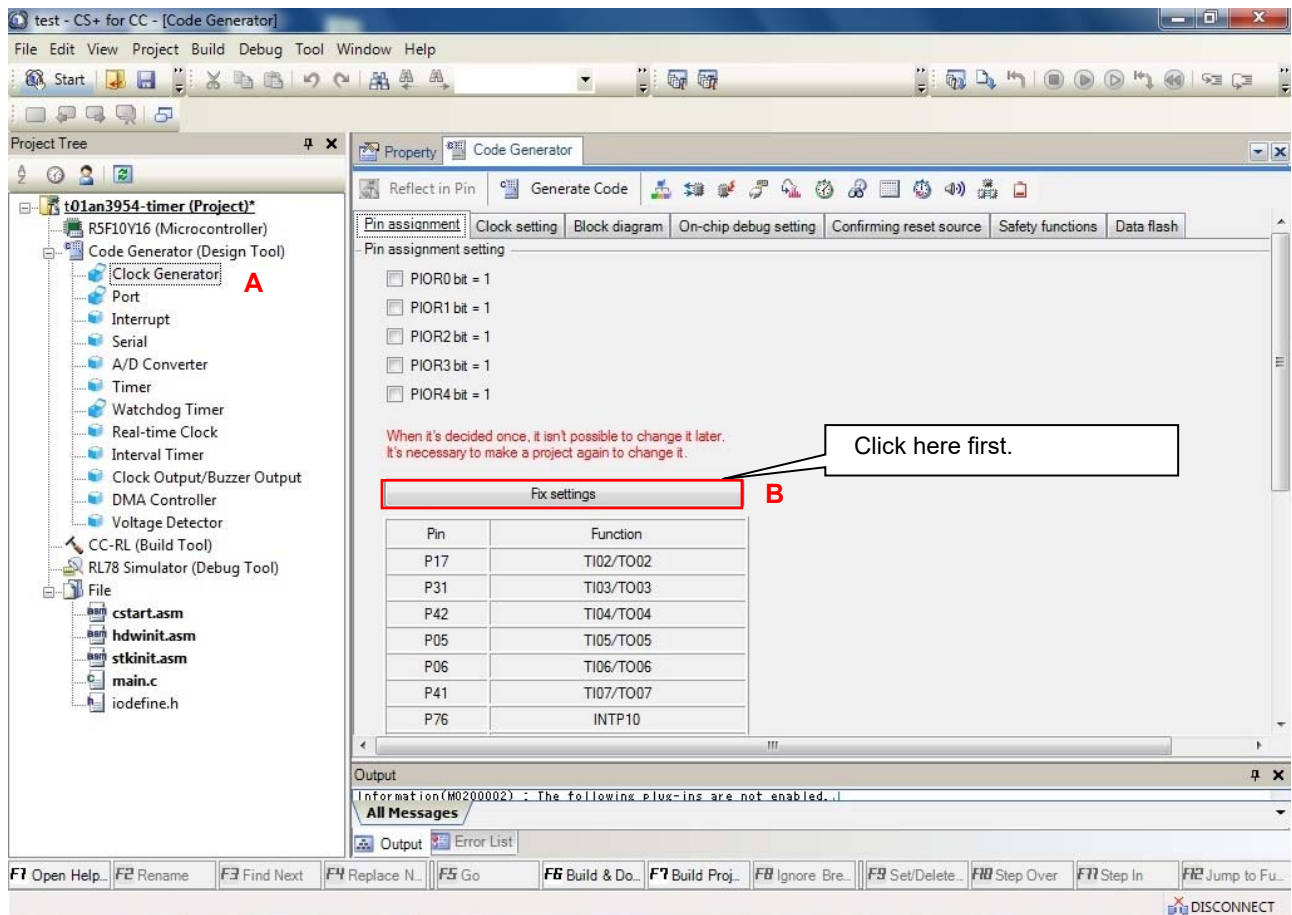


Figure 1.1 Code Generator Setting Window (1)

(3) Refer to the assembly source code to be replaced and set the other functions.

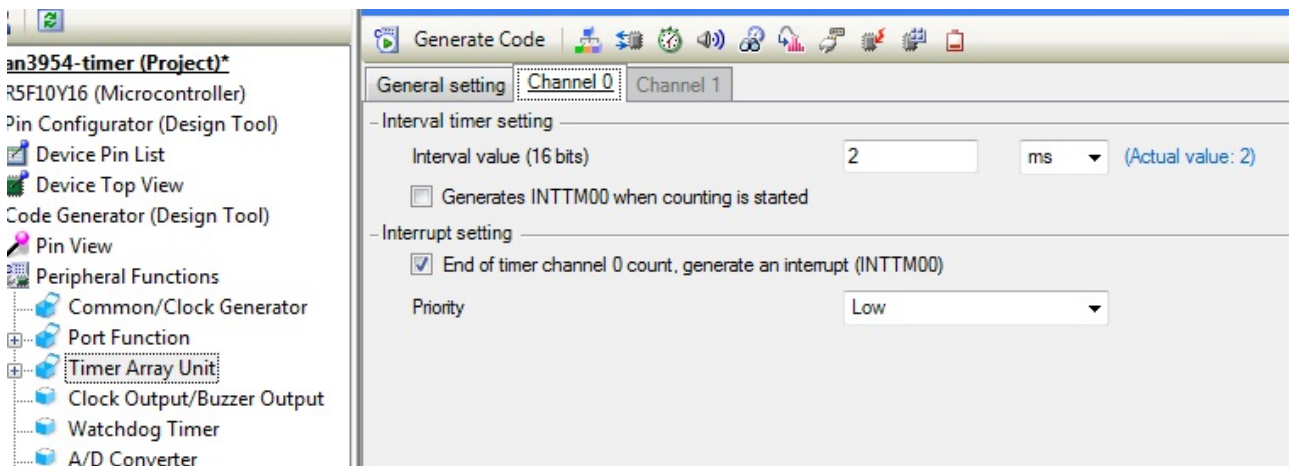


Figure 1.2 Code Generator Setting Window (2)

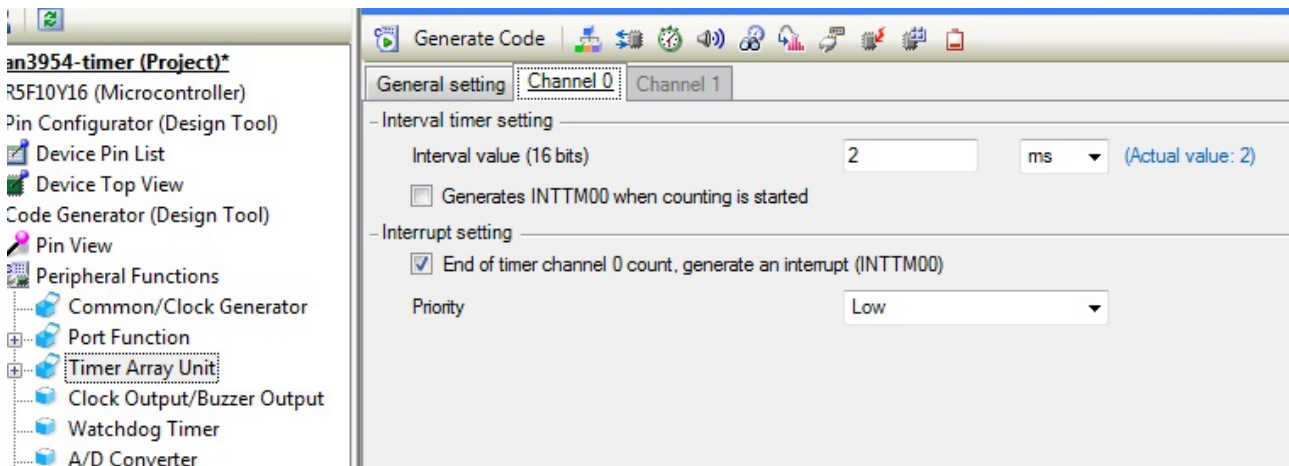


Figure 1.3 Code Generator Setting Window (3)

When settings of all the functions are completed, click the [Generate Code] button on the upper part of the window to activate code generation (automatic generation of the source code) (C in Figure 1.4).

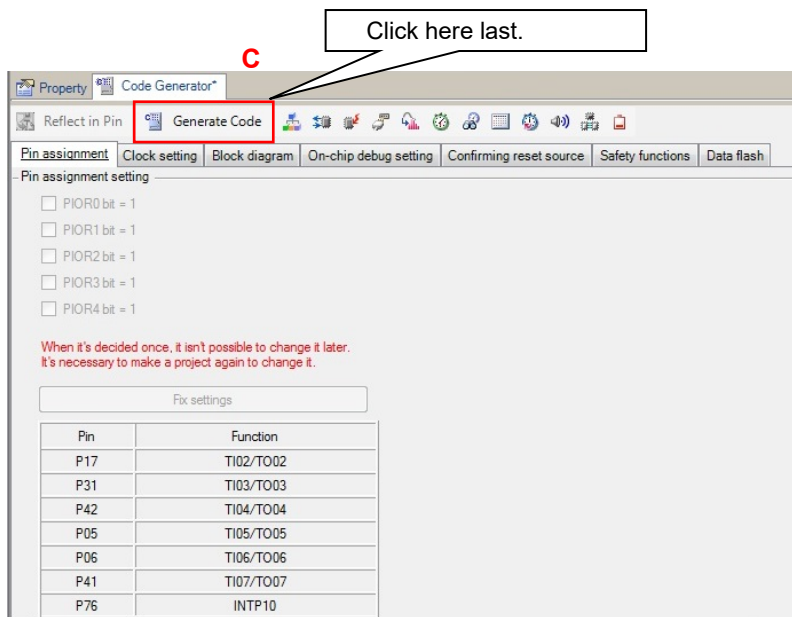


Figure 1.4 Code Generator Setting Window (4)

## 1.2 Definition of Constants and Variables

Since sections cannot be defined in the inline assembler functions, newly define the constants and variables in the C language. (Refer to Table 1.1 and Table 1.2.)

Table 1.1 Changing Constants

Constant Name in Assembly Source	Constant Name in C Source	Contents
TINTVL	g_tdr00_data[]	Value to be set to TDR00 each time the switch is pressed for the specified number of times
T10MSWAIT	g_10ms_count[]	10-ms count value by the timer each time the switch is pressed for the specified number of times

Table 1.2 Changing Global Variables

Constant Name in Assembly Source	Constant Name in C Source	Contents
RSWCNT	g_sw_counter	Counter for counting the number of times the switch is pressed
RTMCNT	g_inttm00_counter	Counter for counting the number of times the timer interrupt is generated
RTDR00	g_tdr00_work	Value to be set to TDR00 each time the timer interrupt is generated 250 times

```

;*****
;
;   data definition
;
;*****
DMAIN      .DSEG  SBSS
RTMCNT:    .DS    1           ; counter of TMOO interrupt
RTM10MS:   .DS    1           ; counter for 10ms
RSWCNT:    .DS    1           ; counter of SW

DTDR       .DSEG  SBSS
RTDR00:    .DS    2           ; TDR00H,TDR00L data

CCHNGLED   .EQU   0x00000001 ; LED change data

;=====
;   constant data for interval
;=====
XMAIN2     .CSEG  TEXT

TINTVL:
           .DB2   PERIOD - 1   ; interval data for 2ms
           .DB2   PERIOD2 - 1  ; interval data for 1ms
           .DB2   PERIOD3 - 1  ; interval data for 0.5ms
           .DB2   PERIOD4 - 1  ; interval data for 0.25ms
           .DB2   PERIOD5 - 1  ; interval data for 0.125ms

```

Figure 1.5 Definition Part in Assembly Source Code

```

/******
Global variables and functions
*****
/* Start user code for global. Do not edit comment generated here */
__saddr uint8_t g_sw_counter = 0U;           /* Variable for counter of SW input */
__saddr uint16_t g_tdr00_work = 0U;         /* Variable of keeping next setting */
__saddr uint8_t ucchat;                      /* 8 bit variable for noise rejection */
/* Compare value table for interval timer */
const uint16_t g_tdr00_data[] =
{
    (40000 - 1),                             /* 2ms interval compare value */
    (20000 - 1),                             /* 1ms interval compare value */
    (10000 - 1),                             /* 0.5ms interval compare value */
    (5000 - 1),                              /* 0.25ms interval compare value */
    (2500 - 1),                              /* 0.125ms interval compare value */
};

/* 10ms wait count value table */
const uint16_t g_10ms_count[] =
{
    (5 + 1),                                 /* For 2ms interval */
    (10 + 1),                               /* For 1ms interval */
    (20 + 1),                               /* For 0.5ms interval */
    (40 + 1),                               /* For 0.25ms interval */
    (80 + 1),                               /* For 0.125ms interval */
};

__saddr uint8_t g_inttm00_counter = 0U;      /* Variable for counter of INTTMOO */
/* End user code. Do not edit comment generated here */

```

Figure 1.6 Definition Part in C Language Source Code

### 1.3 Definition of Inline Assembler Functions

To replace the functional units in the assembly source code with the corresponding inline assembler functions, define the inline assembler functions.

When using the inline assembler functions, define them with "#pragma inline\_asm".

Table 1.3 List of Functions (Subroutines) Used

Function Name	Outline
Inline_asm_mainfunc	MAIN processing
r_invert_ledfunc	Counts the number of INTTM00 generated and reverses the LED display every 250 times.
r_inttm_func	Processes INTTM00 interrupt generated.
r_intp_func	Processes INTP0 interrupt generated.

```

E/*****
Pragma directive
*****
/* Start user code for pragma. Do not edit comment generated here */
#pragma inline_asm inline_asm_mainfunc
#pragma inline_asm r_invert_ledfunc
#pragma inline_asm r_inttm_func
#pragma inline_asm r_intp_func
/* End user code. Do not edit comment generated here */
    
```

Figure 1.7 Example of Function Definition



## 1.4 Migration of Processes in Inline Assembler Functions

Migrate the functional units in the assembly source code to the corresponding functions having been defined in 1.3, Definition of Inline Assembler Functions.

- (1) Migrate certain functional units in the assembly source code (① in Figure 1.8 and ② in Figure 1.10) to the corresponding inline assembler functions (① in Figure 1.9 and ② in Figure 1.11).

```

;*****
;
;   main function
;
;*****
main:
  CLRB   RTMCNT           ; clear loop counter
  CLRB   RSWCNT           ; clear SW counter
  MOVW   AX, ES:!TINTVL   ; get initial interval data
  MOVW   RTDROD, AX       ; copy it to work area
  CALL   !!SSTARTINTV     ; start timer (interval)
  CLR1   PMKO             ; enable INTPO
  EI                                           ; enable interrupt

MAIN_LOOP:
  HALT
  BR     $MAIN_LOOP       ; continue to operation
    
```

Figure 1.8 Assembly Source Code to be Migrated ①

```

;*****
/* main routine */
static void inline_asm_mainfunc(void)
{
;*****
;
;   main function
;
;*****
main:
  CLRB   RTMCNT           ; clear loop counter
  CLRB   RSWCNT           ; clear SW counter
  MOVW   AX, ES:!TINTVL   ; get initial interval data
  MOVW   RTDROD, AX       ; copy it to work area
  CALL   !!SSTARTINTV     ; start timer (interval)
  CLR1   PMKO             ; enable INTPO
  EI                                           ; enable interrupt

MAIN_LOOP:
  HALT
  BR     $MAIN_LOOP       ; continue to operation
}
    
```

Figure 1.9 C Source Code after Migration ①

```

;*****
;
; interrupt function : INTTMOO
; occur every 2ms/1ms/0.5ms/0.25ms/0.125ms
;
;*****
IINTTMOO:
    PUSH    AX
    CALL    !SINTTMOO      ; call actual blinking function routine
    POP     AX
    RETI
    
```

Figure 1.10 Assembly Source Code to be Migrated ②

```

/*****
 * Function Name:r_inttm_func
 * Description : This function interrupt function : INTTMOO
 * Arguments : none
 * Return Value : none
 *****/
void r_inttm_func(void)
{
    *****
    ;
    ; interrupt function : INTTMOO
    ; occur every 2ms/1ms/0.5ms/0.25ms/0.125ms
    ;
    ;*****
    IINTTMOO:
        PUSH    AX
        CALL    !SINTTMOO      ; call actual blinking function routine
        POP     AX
        RETI
    }
    
```

Figure 1.11 C Source Code after Migration ②

(2) Modify the names of the variables, constants, and functions of the inline assembler functions to the newly defined descriptions in C (③ in Figure 1.12 and ③ in Figure 1.13).

(3) Replace the CPU control instructions as described below (④ and ⑤ in Figure 1.12 and ④ and ⑤ in Figure 1.13).

EI → ei, DI → di, HALT → halt, STOP → stop, NOP → nop

```

/* main routine */
static void inline_asm_mainfunc(void)
{
    MOV    ES,    #0                ; for constant data access
    ;*****
    ;
    ;   main function
    ;
    ;*****
main:
    CLR B    RTMONT                ; clear loop counter
    CLR B    RSWCNT                ; clear SW counter
    MOV W    AX,    ES:!TINTVL     ; get initial interval data
    MOV W    RTDROO, AX           ; copy it to work area
    CALL    !!SSTARTINTV          ; start timer (interval)
    CLR I    PMKO                 ; enable INTPO
    EI                      ; enable interrupt

MAIN_LOOP:
    HALT

    BR     $MAIN_LOOP            ; continue to operation
}
    
```

Figure 1.12 C Source Code before Modification

```

/* main routine */
static void inline_asm_mainfunc(void)
{
    MOV    ES,    #0                ; for constant data access
    ;*****
    ;
    ;   main function
    ;
    ;*****
main:
    CLR B    _g_inttm00_counter    ; clear loop counter
    CLR B    _g_sw_counter        ; clear SW counter
    MOV W    AX, ES:!_g_tdr00_data ; get initial interval data
    MOV W    _g_tdr00_work, AX    ; copy it to work area
    CALL    !!_R_TAUD_Channel0_Start ; start timer (interval)
    CLR I    PMKO                 ; enable INTPO
    ei                      ; enable interrupt

MAIN_LOOP:
    halt

    BR     $MAIN_LOOP            ; continue to operation
}
    
```

Figure 1.13 C Source Code after Modification

- (4) When accessing the special function register (SFR) in the inline assembler functions, first exclude "iodefine.h" included in the r\_cg\_macrodriver.h. Then, include "iodefine.h" in each of the C files in which the SFR is accessed.

```

}/******
 * File Name      : r_cg_macrodriver.h
 * Version       : Code Generator for RL78/G10 V1.04.03.03 [07 Mar 2016]
 * Device(s)    : R5F10Y16
 * Tool-Chain   : CCRL
 * Description   : This file implements general head
 * Creation Date: 2017/08/29
*****
#ifndef MODULE_ID_H
#define MODULE_ID_H
}/******
Includes
#include "../iodefine.h"
}/******
Macro definitions (Register bit)
*****

```

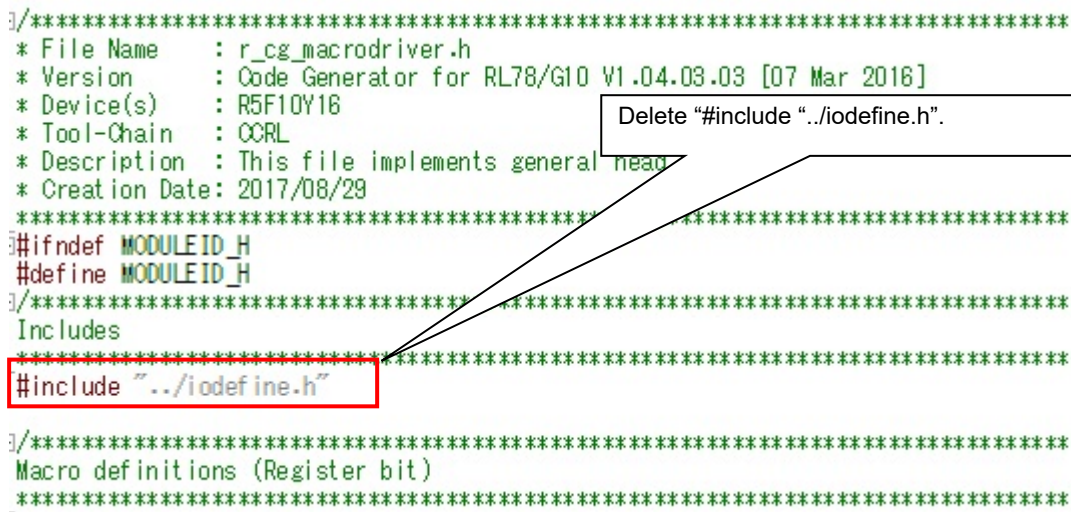


Figure 1.14 Deleting "iodefine.h" (r\_cg\_macrodriver.h)

```

}/******
Includes
*****
#include "r_cg_macrodriver.h"
#include "r_cg_intp.h"
/* Start user code for include. Do not edit comment generated here */
#include "../iodefine.h"
/* End user code. Do not edit comment generated here */
#include "r_cg_userdefine.h"

```

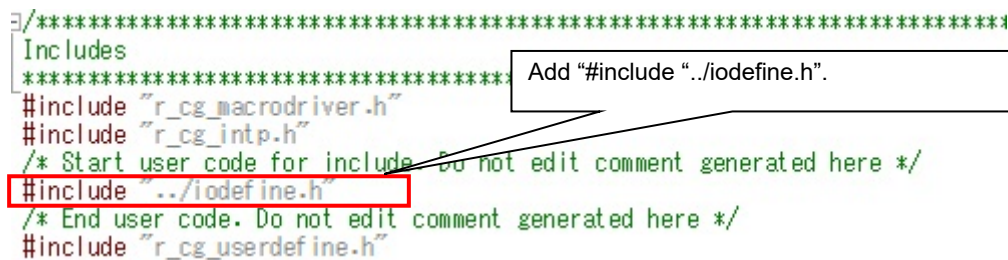


Figure 1.15 Adding "iodefine.h" (r\_cg\_intp.c)

- (5) When calling the inline assembler function in the interrupt process, delete the RETI instruction from the inline assembler function to prevent redundancy of the return instructions from the interrupt process.

```

    □/*****
    * Function Name: r_tau0_channel0_interrupt
    * Description  : This function INTTMO0 interrupt service routine.
    * Arguments   : None
    * Return Value: None
    *****/
    static void __near r_tau0_channel0_interrupt(void)
    □{
        /* Start user code. Do not edit comment generated here */
        r_inttm_func();
        /* End user code. Do not edit comment generated here */
    }

    /* Start user code for adding. Do not edit comment generated here */
    /* End user code. Do not edit comment generated here */
    
```

Figure 1.16 Interrupt Process which has Called Inline Assembler Function (r\_cg\_tau\_user.c)

```

    □/*****
    * Function Name:r_inttm_func
    * Description : This function interrupt function : INTTMO0
    * Arguments : none
    * Return Value : none
    *****/
    void r_inttm_func(void)
    □{
        ;*****
        ; interrupt function : INTTMO0
        ; occur every 2ms/1ms/0.5ms/0.25ms
        ;*****
        IINTTMO0:
        PUSH    AX
        CALL    IINTTMO0 ; call actual blinking function routine
        POP     AX
        RETI
    }
    
```

Delete "RETI".

Figure 1.17 Deleting "RETI" (r\_cg\_main.c)

## 1.5 Calling Inline Assembler Function from main Function

Add the created inline assembler function (inline\_asm\_mainfunc()) to the main function (main()).

```

≡/*****
 * Function Name: main
 * Description  : This function implements main function.
 * Arguments   : None
 * Return Value : None
 *****/
void main(void)
≡{
    R_MAIN_UserInit();
    /* Start user code. Do not edit comment generated here */
    {
        inline_asm_mainfunc();
    }
    /* End user code. Do not edit comment generated here */
}
.....

```

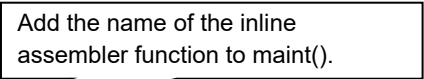


Figure 1.18 r\_cg\_main.c

After completing the above steps, you are ready to migrate the source code from the assembly language to the C language.

## 1.6 Building a Project

Select "Build Project (B)" from the CS+ Build (B) menu to build a project.

If the following message is displayed on the output window, the project has been successfully built.

"===== Ended(Success:1 Projects, Failed:0 Projects)(Tuesday, xxx xx, 2017 xx:xx:xx AM) ====="

If an error message is displayed, debug the project according to the error message displayed.

## 2. Sample Code

The sample code is available on the Renesas Electronics website.

## 3. Reference Documents

User's Manual:

RL78/G10 Initialization CC-RL (R01AN2668E) Application Note

RL78/G10 Timer Array Unit (Interval Timer) CC-RL (R01AN3074E) Application Note

RL78/G10 User's Manual: Hardware (R01UH0384E)

RL78 Family User's Manual: Software (R01US0015E)

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Revision Record	RL78 Software Migration Guide Migration from Assembly Source Code to C Assembly Source Code CC-RL
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Rev.	Date	Description	
		Page	Summary
1.00	Sept. 30, 2017	—	First edition issued
1.01	Jan. 23, 2018	3	Modification Figure 1.1.

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### 1. Handling of Unused Pins

Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

¾ The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

### 2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

¾ The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

### 3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

¾ The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

### 4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

¾ When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

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(Rev.4.0-1 November 2017)



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